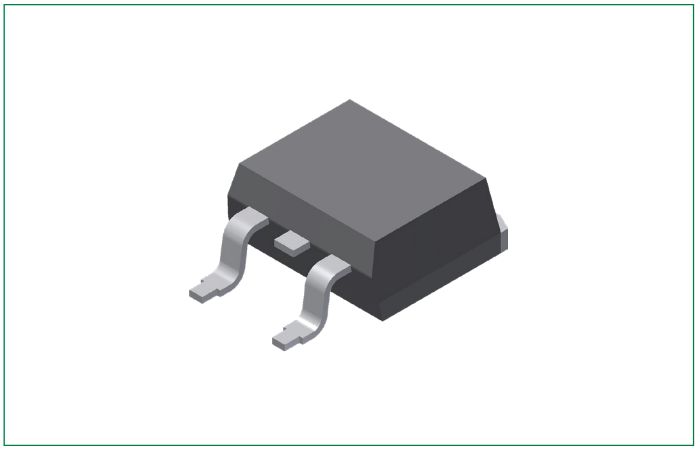
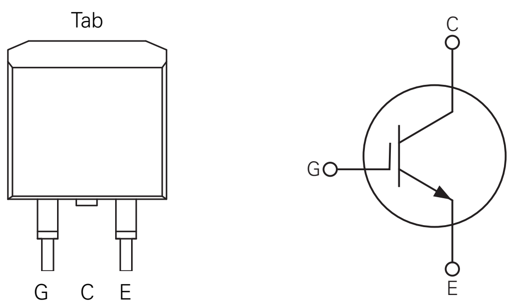
IXYA60N65A5

650 V, 60 A Gen5 XPT™ IGBT

Extreme Light Punch Through IGBT for up to 5 kHz Switching



Pinout Diagrams TO-263 (IXYA)



G: Gate; **C:** Collector; **E:** Emitter; **Tab:** Collector

Description:

Developed using our proprietary XPT™ thin-wafer technology and state-of-the-art Trench IGBT process, these devices feature reduced thermal resistance, low conduction losses, and low gate driver requirements.

Features & Benefits:

- Optimized for Low Conduction Losses
- High Surge Current Capability
- Square RBSOA
- International Standard Package
- Low Gate Charge Q_G
- Low Gate Drive Requirement

Applications:

- Power Inverters
- UPS
- PFC Circuits
- Battery Chargers
- Welding Machines
- Lamp Ballasts
- Inrush Current Protection Circuits

Product Summary

Characteristic	Value	Unit
V_{CES}	650	V
I_{C110}	60	A
$V_{CE(sat)}$	≤ 1.35	V
$t_{fi(typ)}$	110	ns

Maximum Ratings

Symbol	Characteristic	Conditions	Value	Unit
V_{CES}	Collector-Emitter Voltage	T_J = 25 °C to 175 °C	650	V
V_{CGR}	Collector-Gate Voltage	T_J = 25 °C to 175 °C, R_{GE} = 1 MΩ	650	V
V_{GES}	Gate-Emitter Voltage	Continuous	±20	V
V_{GEM}	Transient Gate-Emitter Voltage	Transient	±30	V
I_{C25}	Continuous Collector Current	T_C = 25 °C	134	A
I_{C110}	Continuous Collector Current	T_C = 110 °C	60	A
I_{CM}	Pulsed Collector Current	T_C = 25 °C, 1 ms	260	A
SSOA (RBSOA)	Switching Safe Operating Area (Reverse Biased Safe Operating Area)	V_{GE} = 15 V, T_{VJ} = 150 °C, R_G = 5 Ω, Clamped Inductive Load, $I_{CM} = V_{CE} \le V_{CES}$	108	A
P_C	Collector Power Dissipation	T_C = 25 °C	395	W
T_J	Junction Temperature	–	−55 to 175	°C
T_{JM}	Maximum Junction Temperature	–	175	°C
T_{stg}	Storage Temperature	–	−55 to 175	°C
T_{SOLD}	Soldering Temperature	TO-263-2L - Plastic Body for 10 s	260	°C
F_C	Mounting Force	–	10..65 / 2.2..14.6	N/lb
W	Weight	–	2.5	g

Thermal Characteristic

Symbol	Characteristic	Value			Unit
		Min.	Typ.	Max.	
$R_{th, JC}$	Thermal Resistance, Junction-to-Case	–	–	0.38	°C/W

Electrical Characteristics – Static (T_J = 25 °C unless otherwise specified)

Symbol	Characteristic	Conditions	Value			Unit
			Min.	Typ.	Max.	
BV_{CES}	Collector-Emitter Breakdown Voltage	I_C = 250 µA, V_{GE} = 0 V	650	–	–	V
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	I_C = 250 µA, $V_{CE} = V_{GE}$	3.7	–	5.8	V
I_{GES}	Gate-Emitter Leakage Current	V_{CE} = 0 V, V_{GE} = ±20 V	–	–	±100	nA
I_{CES}	Zero Gate Voltage Collector Current	$V_{CE} = V_{CES}$, V_{GE} = 0 V	–	–	10	µA
		$V_{CE} = V_{CES}$, V_{GE} = 0 V, T_J = 150 °C	–	–	250	µA
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage[1]	I_C = 36 A, V_{GE} = 15 V	–	1.23	1.35	V
		I_C = 36 A, V_{GE} = 15 V, T_J = 150 °C	–	1.35	–	V

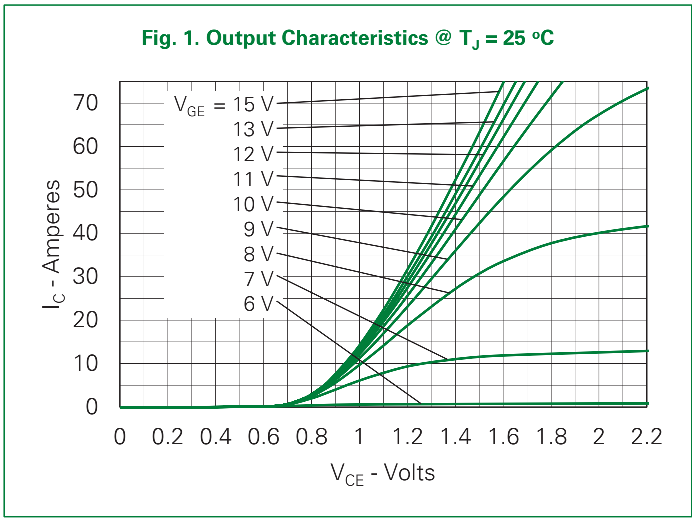
Note 1: Pulse test, t ≤ 300 µs, duty cycle, d ≤ 2%

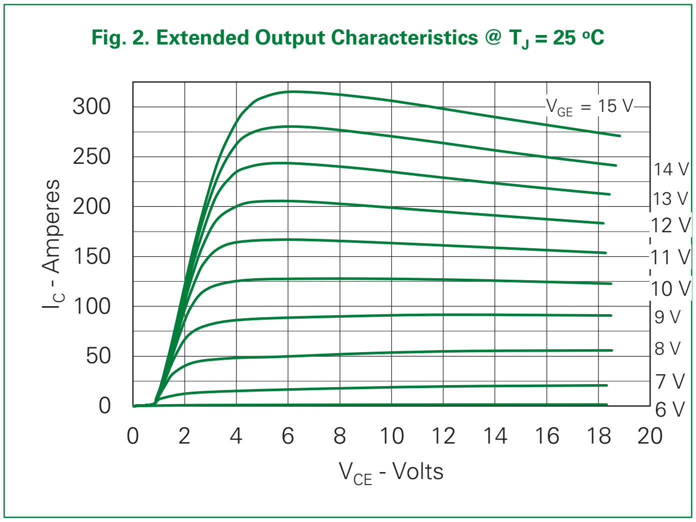
Electrical Characteristics – Dynamic (T_J = 25 °C unless otherwise specified)

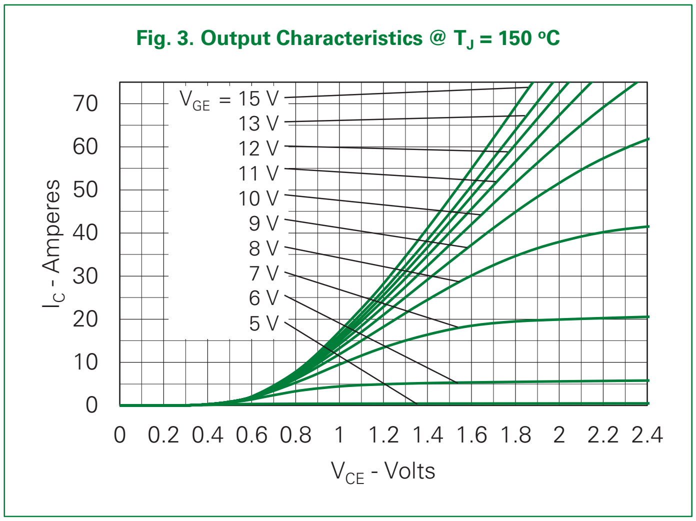
Symbol	Characteristic	Conditions		Value			Unit
				Min.	Typ.	Max.	
g_{fs}	Transconductance[1]	I_C = 36 A, V_{CE} = 10 V		20	35	–	S
C_{ies}	Input Capacitance	V_{GE} = 0 V, V_{CE} = 25 V, f = 1 MHz		–	1970	–	pF
C_{oes}	Output Capacitance			–	106	–	
C_{res}	Reverse Transfer Capacitance			–	80	–	
$Q_{g(on)}$	Total Gate Charge	V_{GE} = 15 V, V_{CE} = 0.5 x $V_{CES,}$ I_C = 36 A		–	128	–	nC
Q_{ge}	Gate-Emitter Charge			–	13	–	
Q_{gc}	Gate-Collector Charge			–	66	–	
$t_{d(on)}$	Turn-on Delay Time[2]	Inductive Load, V_{GE} = 15 V, V_{CE} = 400 V, I_C = 36 A, $R_{G(ext)}$ = 5 Ω	T_J = 25 °C	–	28	–	ns
			T_J = 150 °C	–	19	–	
t_{ri}	Turn-on Rise Time[2]		T_J = 25 °C	–	32	–	ns
			T_J = 150 °C	–	32	–	
E_{on}	Turn-on Energy[2]		T_J = 25 °C	–	0.60	–	mJ
			T_J = 150 °C	–	1.10	–	
$t_{d(off)}$	Turn-off Delay Time[2]		T_J = 25 °C	–	230	–	ns
			T_J = 150 °C	–	235	–	
t_{fi}	Turn-off Fall Time[2]		T_J = 25 °C	–	110	–	ns
			T_J = 150 °C	–	240	–	
E_{off}	Turn-off Energy[2]		T_J = 25 °C	–	1.45	–	mJ
			T_J = 150 °C	–	2.50	–	

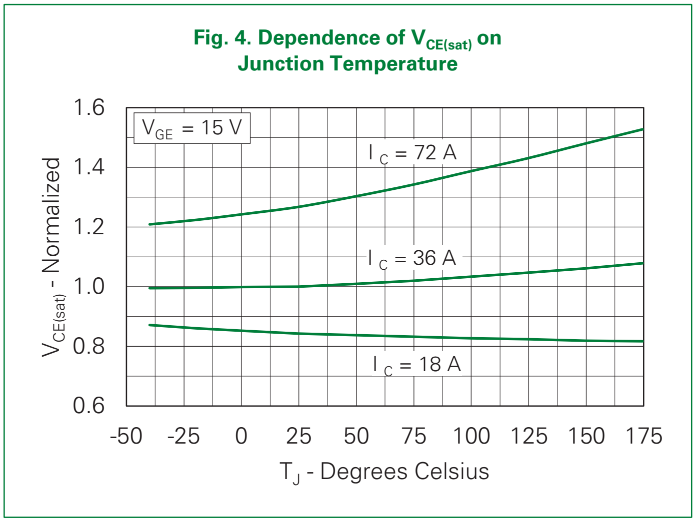
Note 1: Pulse test, t ≤ 300 μs, duty cycle, d ≤ 2%
Note 2: Switching times and energy losses may increase for higher $V_{CE(clamp)}$, T_J, or R_G.

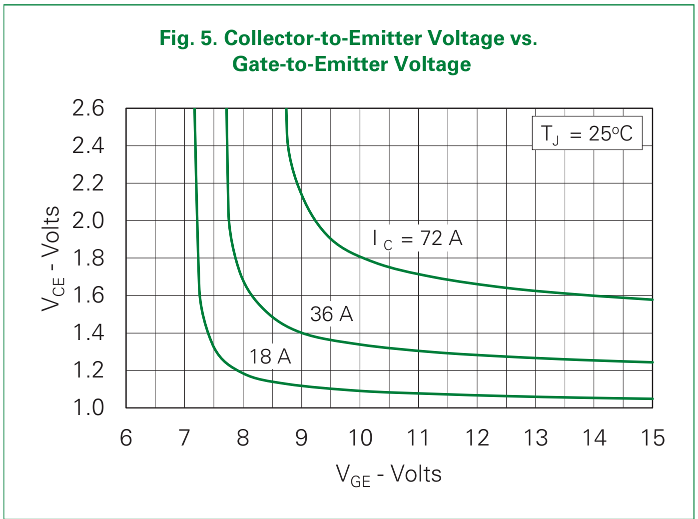
Characteristic Curves











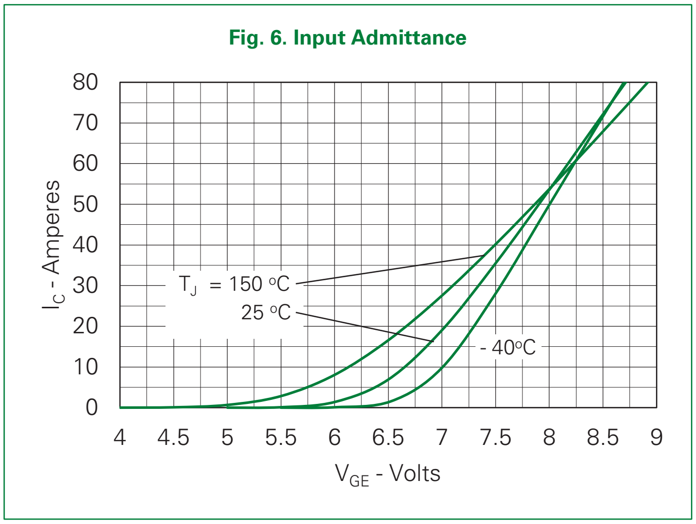


Fig. 7. Transconductance

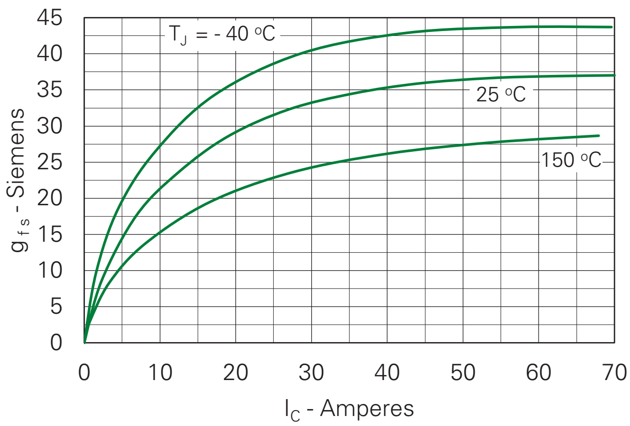


Fig. 8. Gate Charge

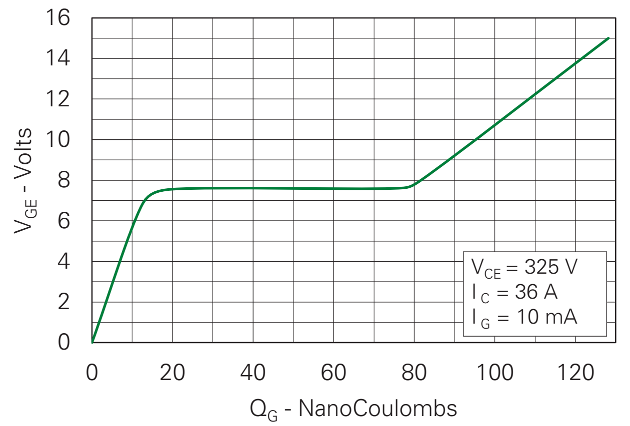


Fig. 9. Capacitance

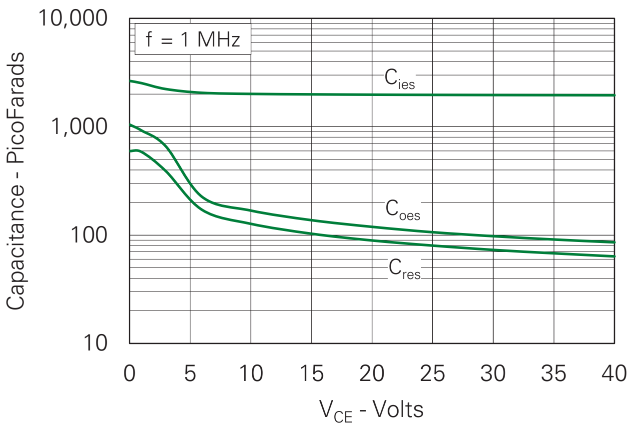


Fig. 10. Reverse-Bias Safe Operating Area

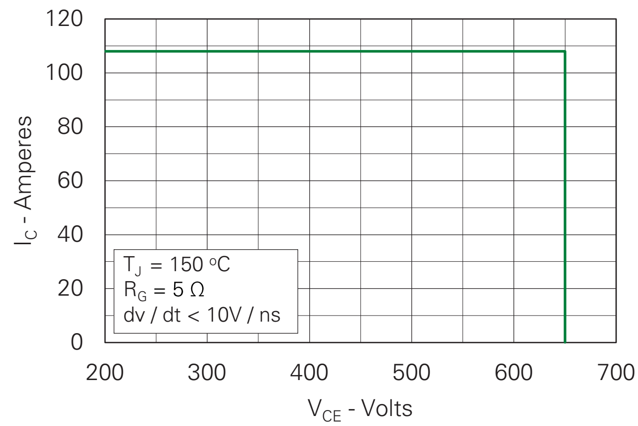


Fig. 11. Maximum Transient Thermal Impedance

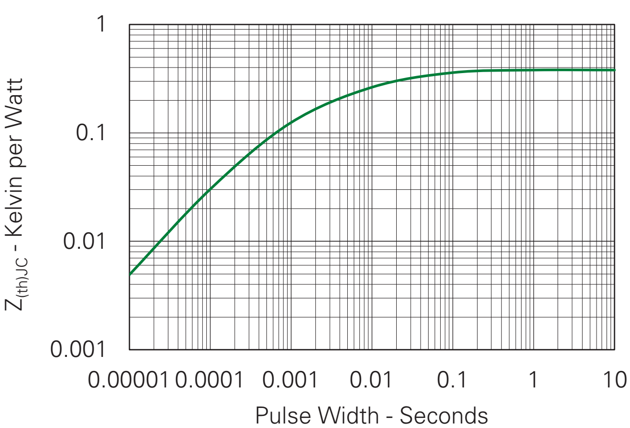


Fig. 12. Inductive Switching Energy Loss vs. Collector Current

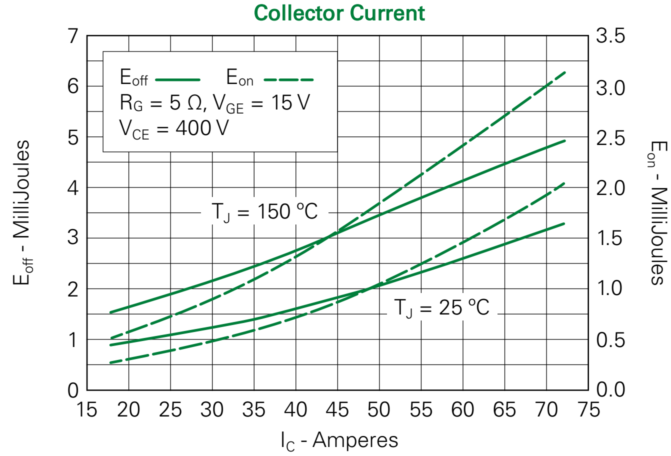


Fig. 13. Inductive Switching Energy Loss vs. Gate Resistance

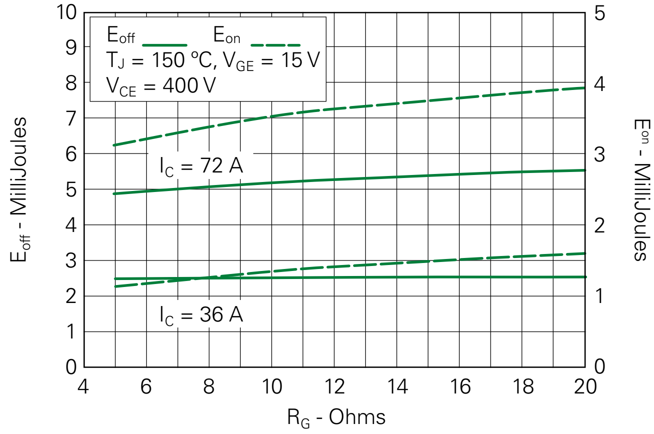


Fig. 14. Inductive Switching Energy Loss vs. Junction Temperature

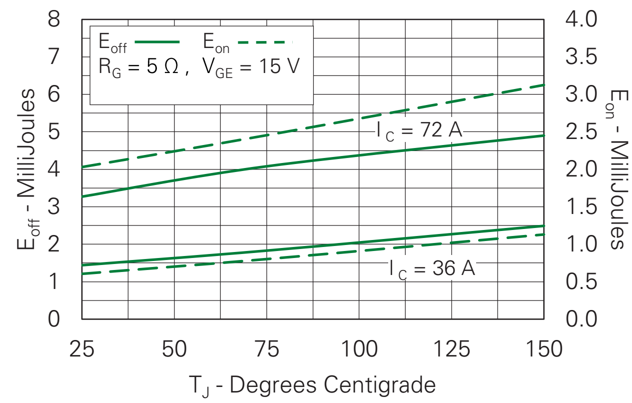


Fig. 15. Inductive Turn-off Switching Times vs. Gate Resistance

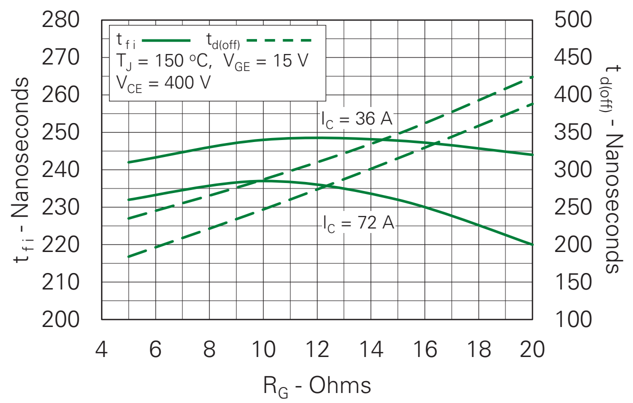


Fig. 16. Inductive Turn-off Switching Times vs. Collector Current

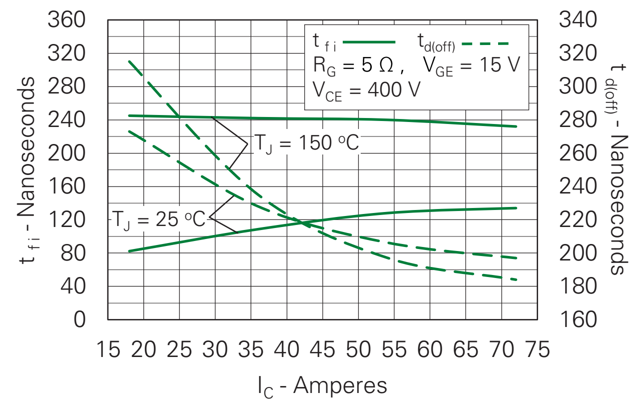


Fig. 17. Inductive Turn-off Switching Times vs. Junction Temperature

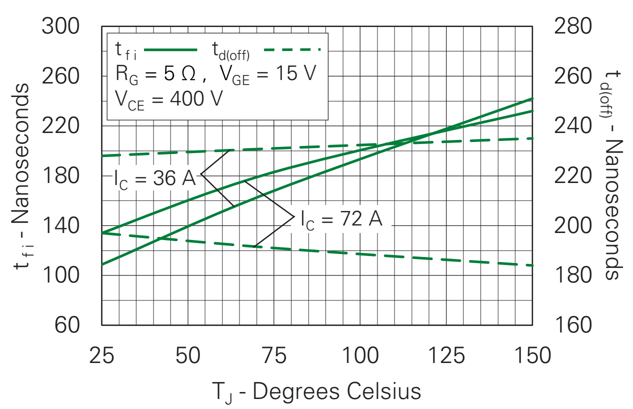


Fig. 18. Inductive Turn-on Switching Times vs. Gate Resistance

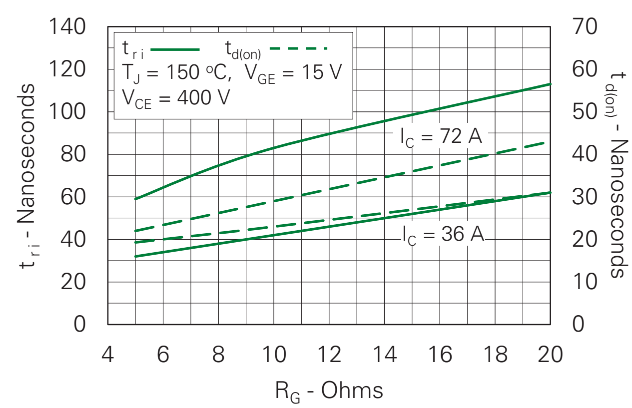


Fig. 19. Inductive Turn-on Switching Times vs. Collector Current

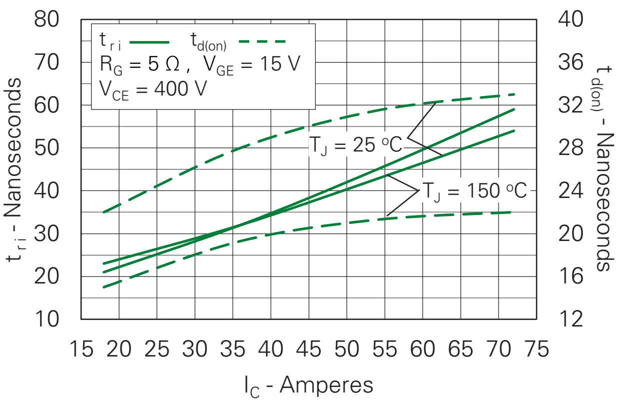
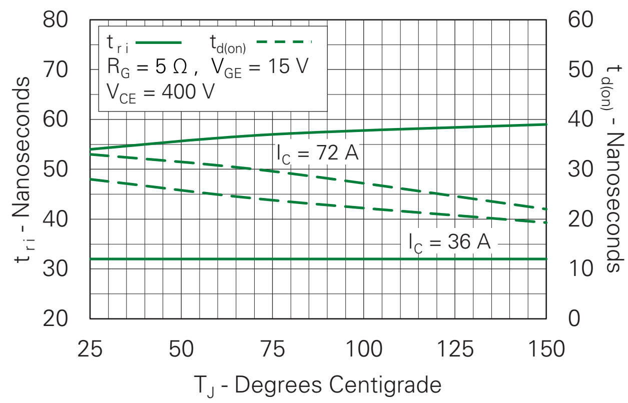
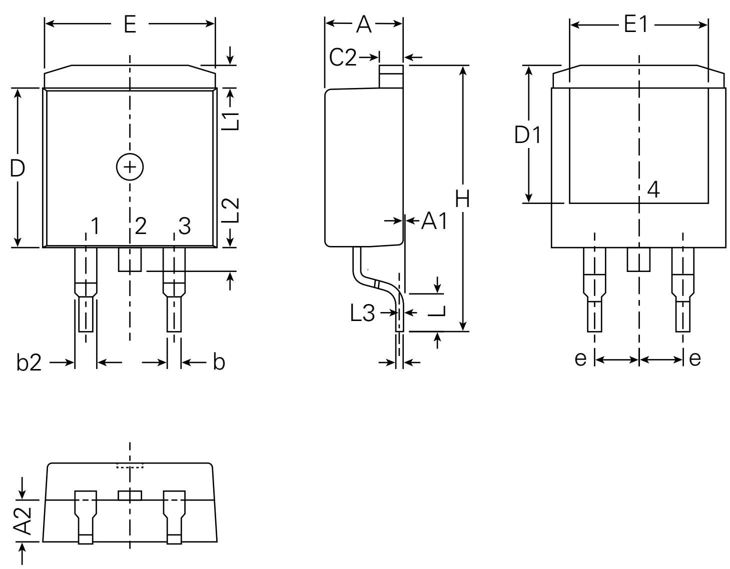


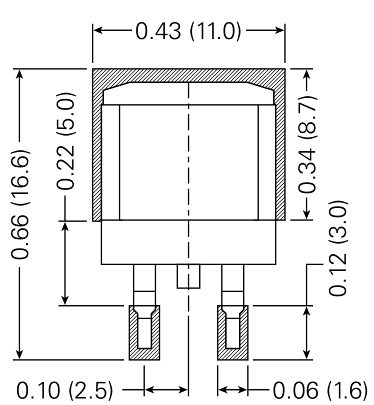
Fig. 20. Inductive Turn-on Switching Times vs. Junction Temperature



Part Outline Drawings TO-263 (IXYA)



Symbol	Inches		Millimeters	
	Min.	Max.	Min.	Max
A	0.170	0.185	4.30	4.70
A1	0.000	0.008	0.00	0.20
A2	0.091	0.098	2.30	2.50
b	0.028	0.035	0.70	0.90
b2	0.046	0.060	1.18	1.52
c	0.018	0.024	0.45	0.60
C2	0.049	0.060	1.25	1.52
D	0.340	0.370	8.63	9.40
D1	0.300	0.327	7.62	8.30
E	0.380	0.410	9.65	10.41
E1	0.270	0.330	6.86	8.38
e	0.100 BSC		2.54 BSC	
H	0.580	0.620	14.73	15.75
L	0.075	0.105	1.91	2.67
L1	0.039	0.060	1.00	1.52
L2	–	0.070	–	1.77
L3	0.100 BSC		0.254 BSC	



MINIMUM PCB FOOT PRINT LAYOUT

REVISION HISTORY

08/03/2023	XZ	▪ New Datasheet. Version 0.4
08/09/2023	XZ	▪ Updated product outline drawing. Updated dimensions table. Split IXYA60N65A5 as a separate datasheet.